Gudeng Precision Industrial Co. Ltd
家登精密工業股份有限公司

2025.03

Partner with H.E.A.R.T. , Grow with P.A.S.S.I.O.N.

COO & Spokeswoman Amy Shen
(02)2268-9141
AmyShen@gudeng.com

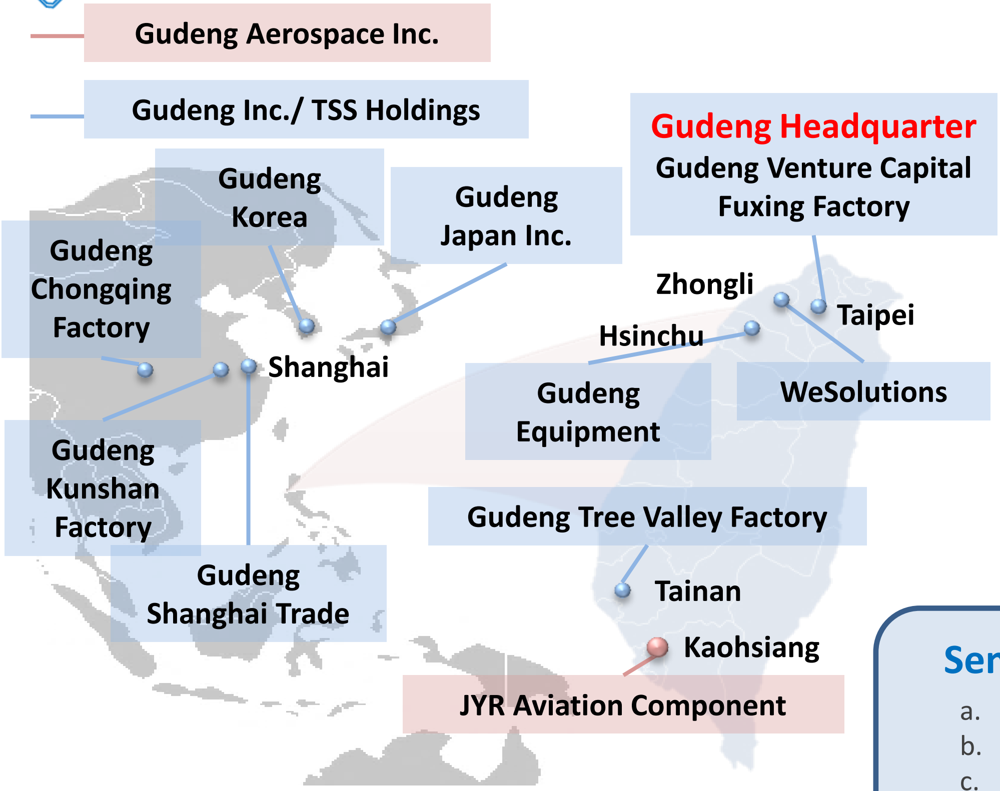
Safe Harbor Notice

Gudeng

This presentation includes forward-looking statements. Forward-looking statements refer to statement that address activities, events or developments that Gudeng Precision expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates, market share, total addressable market (TAM) and business plans).

Gudeng’s forward-looking statements are subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements. Gudeng does not undertake any obligation to publicly update any forward-looking statement to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Gudeng Company Overview



- ▶Established：Mar. 20th , 1998
- ▶Employee： 1100 up
- ▶Capital：US$ 30 million
- ▶2020 Group Revenue：US$ 83 million
- ▶2021 Group Revenue：US$ 104 million
- ▶2022 Group Revenue： US$ 150 million
- ▶2023 Group Revenue： US$ 162 million (13% growth)
- ▶2024 Group Revenue： US$ 218 million (29% growth)

Semiconductor

a. Mask Handling Solutions
b. Wafer Handling Solutions
c. Equipment
d. Other Service

Aerospace

a. Hydraulic Cylinders
b. Heat Conduction Tubes
c. Dynamic Balancing Motor
d. Thermal Conductivity Bead

Gudeng

Semiconductor Industry Outlook

Gudeng

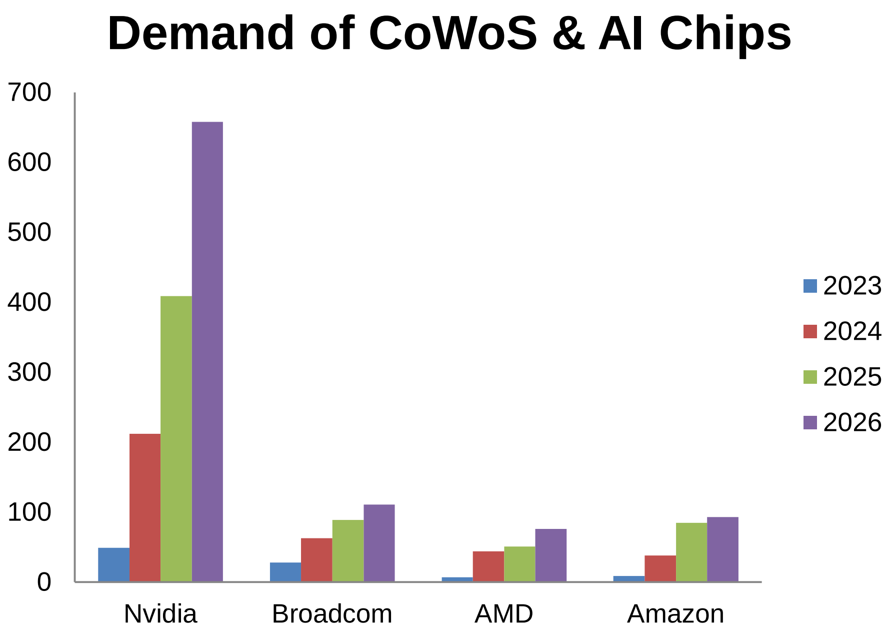
Due to the continuous increase in global demand for AI and HPC in 2025, major application markets from cloud data centers and terminal devices to specific industry categories are facing a trend of upgrading specifications. It is expected that the overall semiconductor market will **grow by more than 15% in 2025**. On top of that, the global semiconductor market will reach a scale of 700-800 billion US dollars by 2027, and there is a consensus in the industry that the market is expected to **exceed 1 trillion US dollars by 2030**.

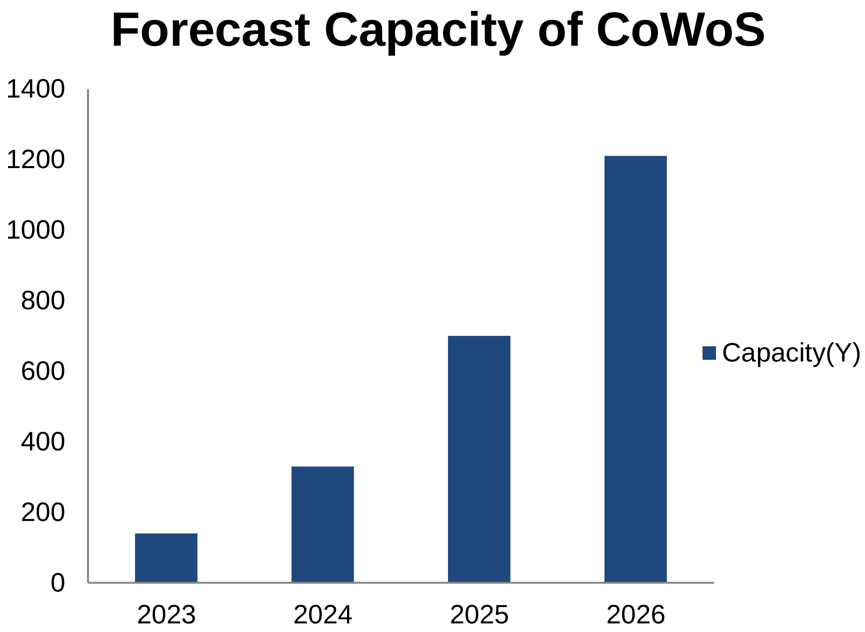
AI Applications will accelerate the development of logic chips, memory, and packaging technologies, in order to improve the overall performance and power efficiency of chips, CoWoS Advanced packaging technology also plays a key role in integrating computing chips and memory. In addition, heat dissipation has become an important part of supporting the stable operation of electronic products under high-efficiency computing systems. Various factories have begun to plan and introduce different heat dissipation solutions to drive the development of related supply chains. In the future, with **generative AI**, the sustained demand for semiconductor technology from other high-speed computing applications will bring significant market growth in **advanced processes and 3D packaging** technology.

Source: MIC、IDC Research

Development Plan of Advance Packing

Gudeng





With increase demand of high-performance chips, it is estimated that the **monthly production capacity** of key customers in CoWoS will reach **70K by the end of 2025** and **exceed 100K by the end of 2026**

Source: GFHK

Key Customer Advance Packaging Plan

Gudeng

Japan Fab(P1~P2)
6/7/12/16/22/28 Nano
P1: Start production by end of 2024
P2: Start production by end of 2027

Fab20(P1~P4)
2 Nano
Start production by 2025
AP1(RD)

Invest 100 B US dollars
3 Fabs
2 AP Facilities
1 RD Center

WA
Fab 11

Germany Fab
12/16/22/26 Nano
Start production by 2027

Chiayi Fab
Expand Advance Packaging
Start production by 2026

CA
RD Center

TX
RD Center

Fab18(P1~P8)
5/4/3 Nano
Expanding 3 Nano
AP2/ AP8 (Start in end of 2025)

Taichung Fab
2 Nano
Finished by 2027
AP5
Start in first half of 2025

Fab21(P1~P3)
4/3 Nano
P1: Start production by 2025
P2: Start production by 2028
P3: Start production by 2030

Fab22(P1~P3)
2 Nano
Start in second half of 2025

Source: CNA/ Digital Times

Local Supply Chain Alliance_TSS

"Integrated service provider of innovative critical material technology"
Build Taiwan Semiconductor Team

Gudeng

Gudeng Group
Gudeng Equipment
3680/ 6953
Global Semiconductor Carrier solution

Symtek
6438
Advanced system equipment storage and positioning system
Gudeng Holding 8.57%

Asia Neo
4542
CoWoS Carrier Cleaning equipment
Gudeng Holding 7.61%

Microprogram
7721
EUV precision sensing instrument
Gudeng Holding 7.99%

Ecosystem Total Solution

Create a flexible and efficient service platform

GreenFiltec
6823
Ultra-high cleanliness and clean room filter material

Yeedex
7556
Key component of EUV yield improvement

ChyiDing
6849
Precision process environmental control
Gudeng Holding 1.72%

Santa Phoenix
Micro pollution prevention and control

Local Supply Chain Alliance_TSS II

Gudeng

"Integrated service provider of innovative critical material technology"
Build Taiwan Semiconductor Team

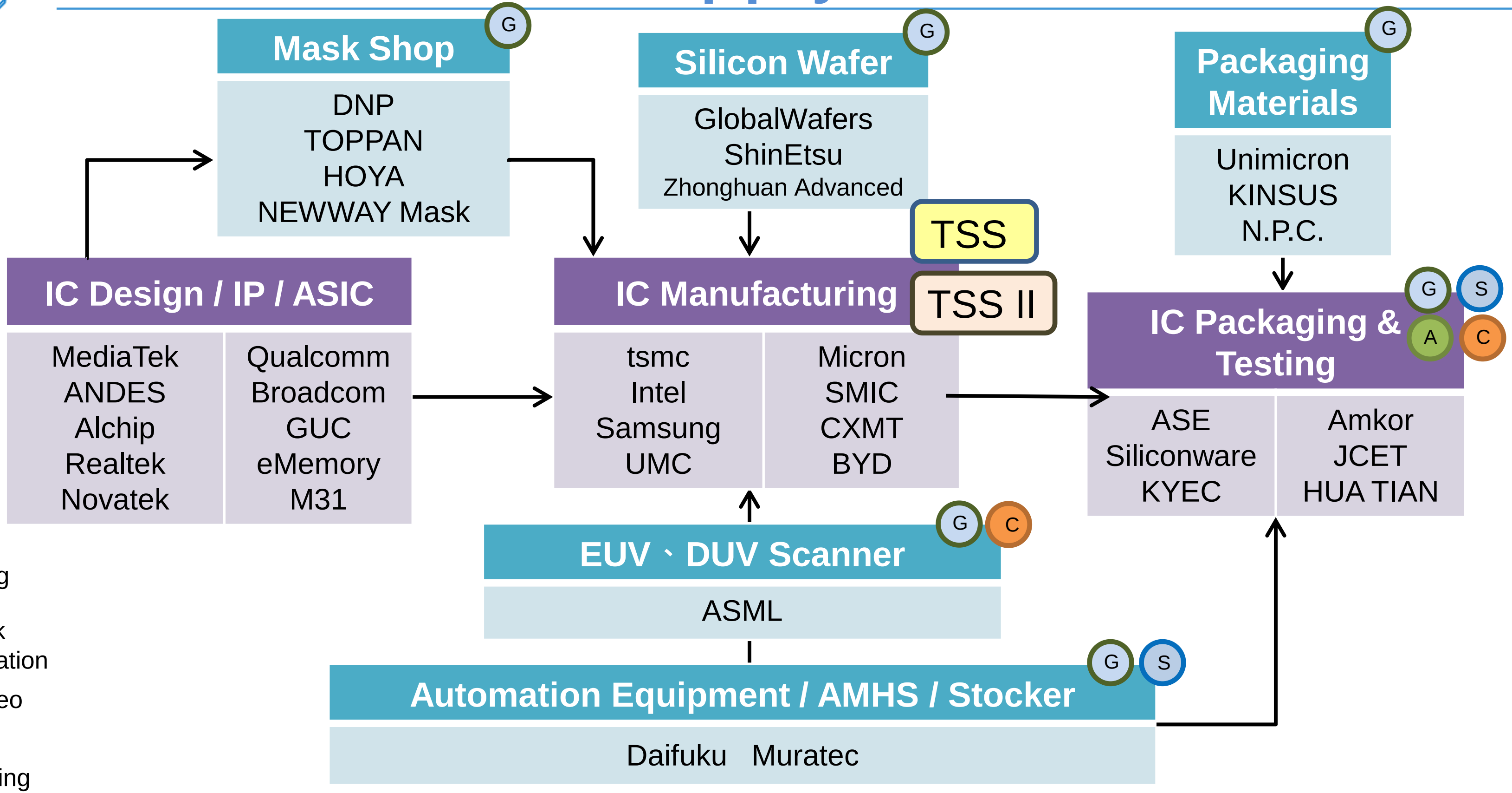
Gudeng

Ecosystem Total Solution

Create a flexible and efficient service platform

SynPower 6658	Precision process & testing machine
Aplex 6570	Industrial intelligence applications and factory
PVI 7768	Key Consumables In Semiconductor
AEMC 4749	Electronic Specialty Chemist material
Fusion Tech	Precision manufacturing, testing and R&D
Concord	High-tech electronic pure water system
Nytex (Gudeng Holding 5%)	Key material for advanced process and packaging
EISO 5291	High-speed and low-loss PCB applications
AblePrint 7734	Key component of AP yield improvement
UVAT 3580	Application and hemical coating expert

Semiconductor Supply Chain



G Gudeng

S Symtek Automation

A Asia Neo Tech

C Chyi Ding

Development of AP in Greater China

With geopolitical uncertainty between China and US, The US government has imposed multiple AI import and export restrictions toward chips. This encouraged manufacturers in Greater China to develop advanced processes to increase local production capacity.

Company	Location	Tech	Capacity (M)		Company	Location	Tech	Capacity (M)
SMIC	Shanghai	7 nm and below	50K		CXMT	Hefei/ Beijing	DRAM	300K
SMIC	Beijing	7 nm / 14 nm	50K		CXMT	Shanghai	DRAM	＞100K
HLMC	Shanghai	7 nm	20K		YMTC	Wuhan	NAND	300K
HUAWEI	Shanghai	7 nm	20K		YMTC	Wuhan	DRAM	50K
HUAWEI	Shenzhen	7 nm / 14 nm	30-50K		Swaysure	Shenzhen	DRAM	100K

Source: GFHK

The capacity goal of key customers in Greater China

The capacity of advanced processes is expected to exceed **150K per month.**

Gudeng 2025 Greater China Market

Gudeng

Gudeng

Shandong
- SiEn(Qing Dao)(8” /12”)
- Qingdao Matter (12”)
- Jinan BYD(8”)
- Qingfang Technology (Blank)
- Jinan Quanyi(Mask)

- **Huawei Group**

Zhejiang
- Hangzhou HFC(12”)
- FullSemi(12”)
- Zhejiang Chuangxin(12”)
- Hangzhou Silan(8”)
- JCET(Shaoxing) (Back End)

Chongqing
- Chongqing Alpha and Omega(12”)
- Resources West Microelectronics(12”)

Jiangsu
- Nanjing TSMC(12”)
- Maxscend(12”)
- SK hynix(8” /12”)
- JCET(Back End)
- Shenzhen Zhicheng (Back End)
- Silicon Integrity(Back End)
- Wuxi ZhongWei(Mask)
- Wuxi Dis(Mask)

Chengdu
- Chengdu Luwei(Mask)
- Chengdu BYD(12”)

Guangdong
- SwaySure(12”)
- Shenzhen Pensun(12”)
- Shenzhen Pengxin Micro(12”)
- Plextron(12”)
- Guangzhou Cansemi(12”)
- Shenzhen SMIC(12”)
- Dgrayxin(Back End)
- Guangzhou NewRay (Mask)
- Shenzhen Newway(Mask)
- Shenzhen Qingyi(Mask)
- Zhuhai Longtu(Mask)

Beijing/Tianjin
- Beijing SMIC(12”)
- Changxin Jidian(12”)
- Beijing YanDong (8” /12”)
- Beijing Selex(8”)
- Tianjin SMIC(8”)

Fujian
- Xiamen United Semi(12”
- JHICC(Jinhua) (12”)
- Xiamen Silan(12”)
- Quliang Electronics
- (Back End)
- PDMCX(mask)

Liaoning
- Intel Dalian(12”)

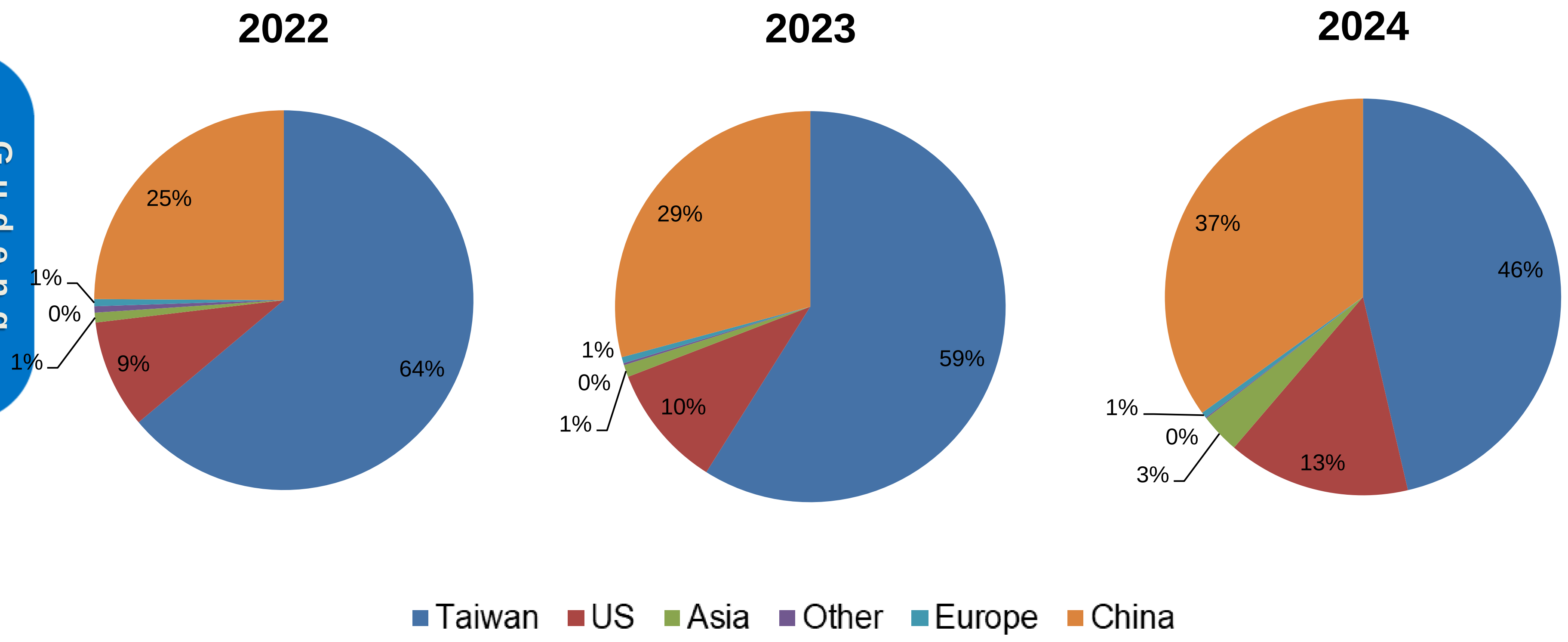
Shaanxi
- Xian ESWIN(Wafer)

Hubei
- Wuhan Chuxing(12”)
- ChangXin Memory(12”)
- Wuhan Global Sensor(8”)
- Yangtze Memory(12”)

Shanghai
- SMIC(12”)
- Shanghai GTX(12”)
- ICRD(12”)
- GTA(8” /12”)
- TSMC Fab10(8”)
- Advanced Semi(8”)
- Shanghai Toppan(Mask)
- Shanghai Zing(Wafer)
- Shanghai AST(Wafer)

Anhui
- Changxin Xinqiao(12”)
- ChangXin Memory(12”)
- Nexchip(12”)
- Hefei Shiya(12”)
- Heifei Payton(Back End)
- Hefei Qingyi(mask)
- Heifei Nexchip(mask)

Gudeng Revenue Regional Distribution



Distribution of Gudeng's Customers

Gudeng

Logic/Power Foundry&IDM.

Memory Foundry&IDM.

Equipment

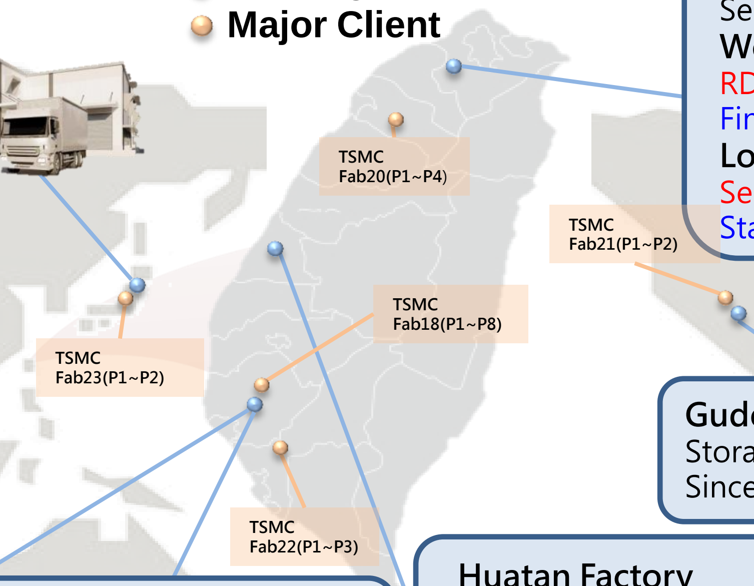
PCB/OSTA (Outsourced Semiconductor Assembly and Test)

Reticle /Mask

Gudeng Expansion Plan

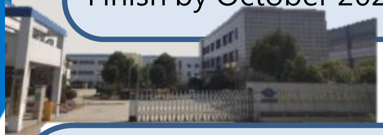
Gudeng

Major Client



Kurume Factory
Semiconductor & Aerospace
Finish by Q2 2027

Kunshan & Chongqing Factory
Semiconductor
Kunshan Factory II
Semiconductor
Finish by October 2024



Fuxing Factory
Semiconductor
WeSolutions Headquarter
RD/ Production for Cooling
Finish by Q2 2025
Longfu Factory I & II
Semiconductor & Aerospace
Start by Q4 2025

Gudeng US
Storage/ FAE
Since January 2024

Tree Valley Factory I
Semiconductor & Aerospace
Tree Valley Factory II
Semiconductor & Aerospace
Clean Room(3F) start in December 2024
1F/ 2F/4FStart production in July 2025

ST Science Park Factory
Semiconductor & Aerospace
Finish by Q1 2029

Huatan Factory
New business
Finish by Q2 2028

Gudeng

2023/6/12

Gudeng Total Solutions

Semiconductor Production Process

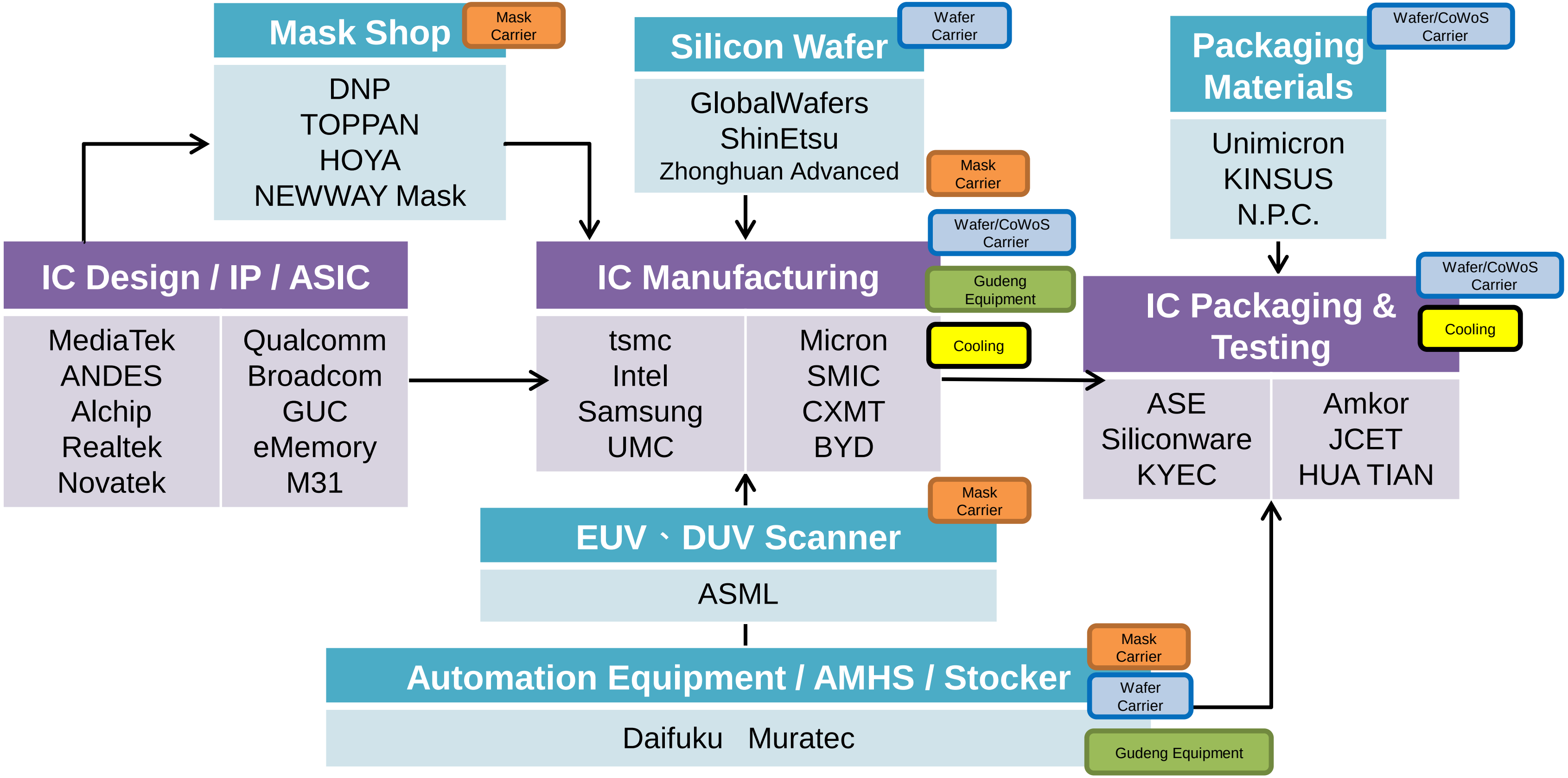
Gudeng

- AI
- Aerospace
- Communication
- Automotive
- Consumer Electronics
- National Defense
- PC/NB

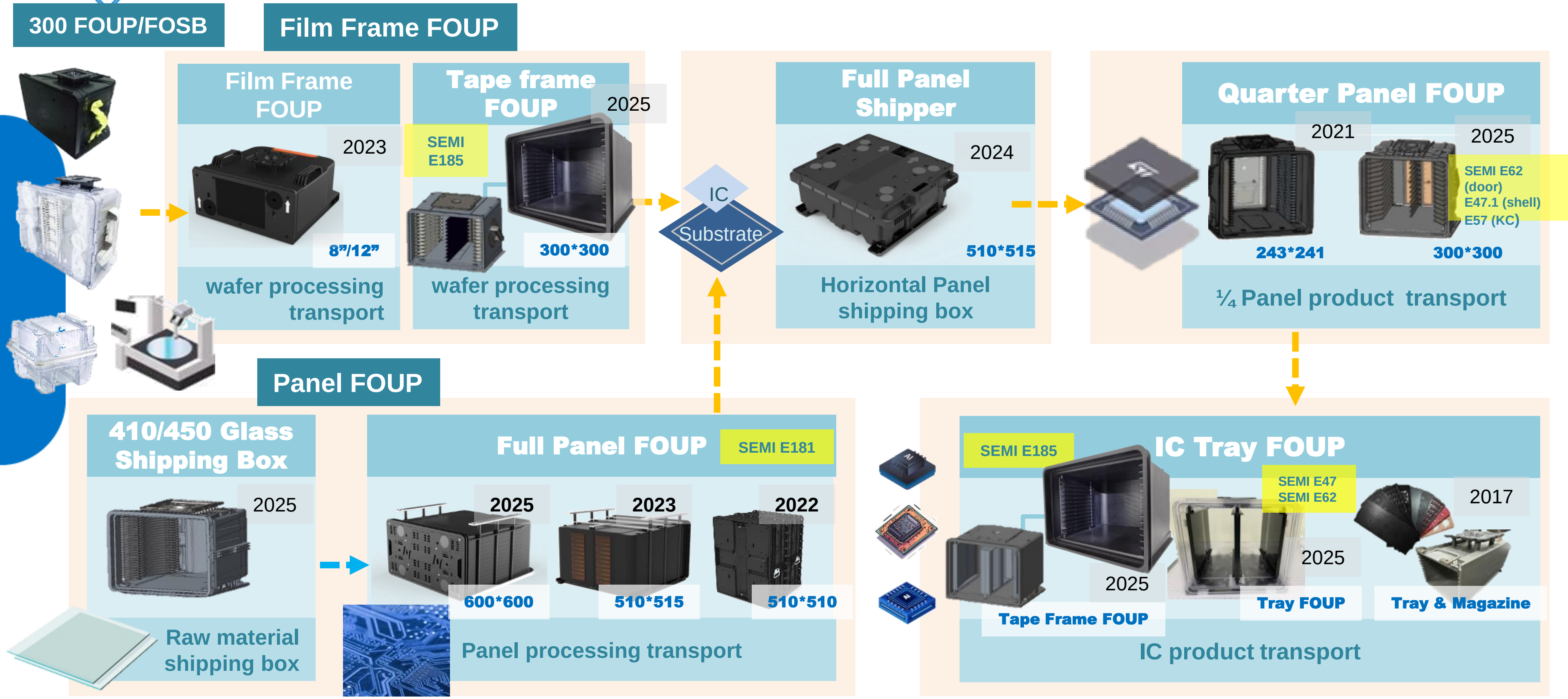
Product Design	Front End	Back End	Board Assembly
IC Design / Mask Maker	Foundry	Packaging / Final Test	Board Assembly / Board Testing
• Circuit Design • Engineering Test	• Materials Fab • Wafer Bank	• Wafer Bumping • Wafer Probing	• Module, Board Assembly & Test

Semiconductor Supply Chain

Gudeng

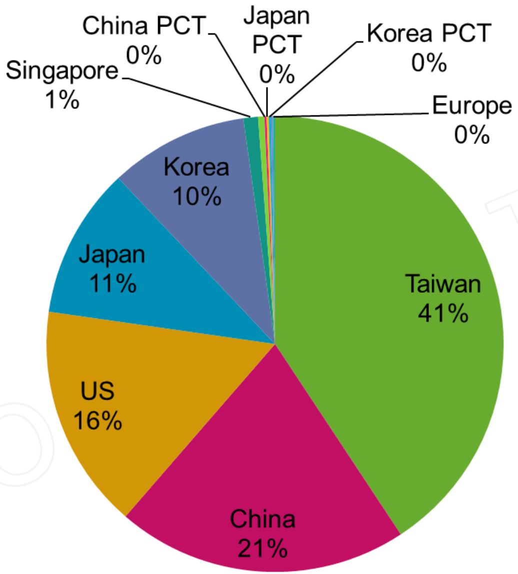


Advance Packaging Product Line

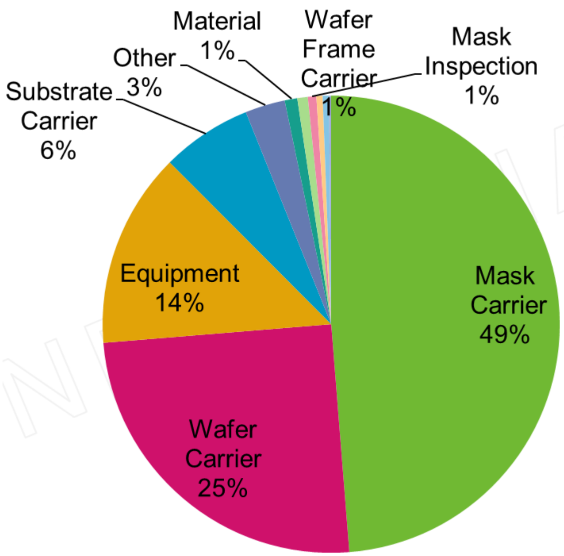


Gudeng Patent

Location



Product

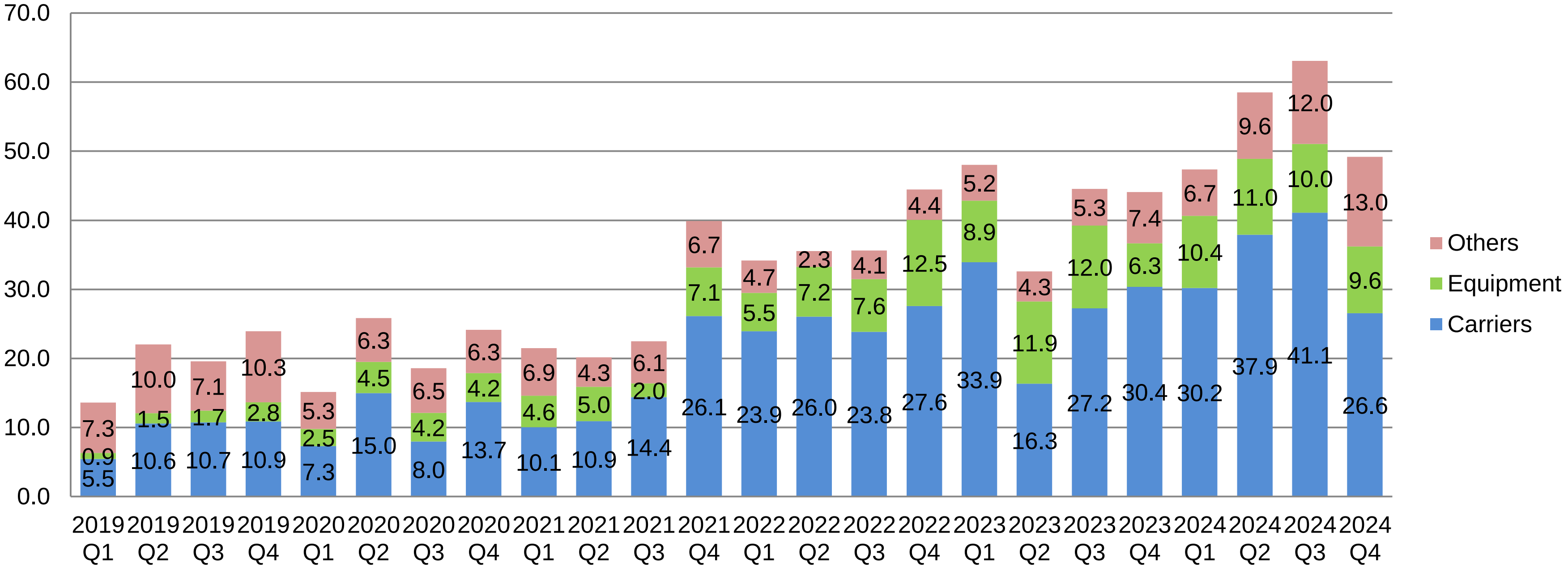


As of March 2025, obtain 702 patent and continue to build a high-tech patent layout

Gudeng Group Revenue (Quarterly)

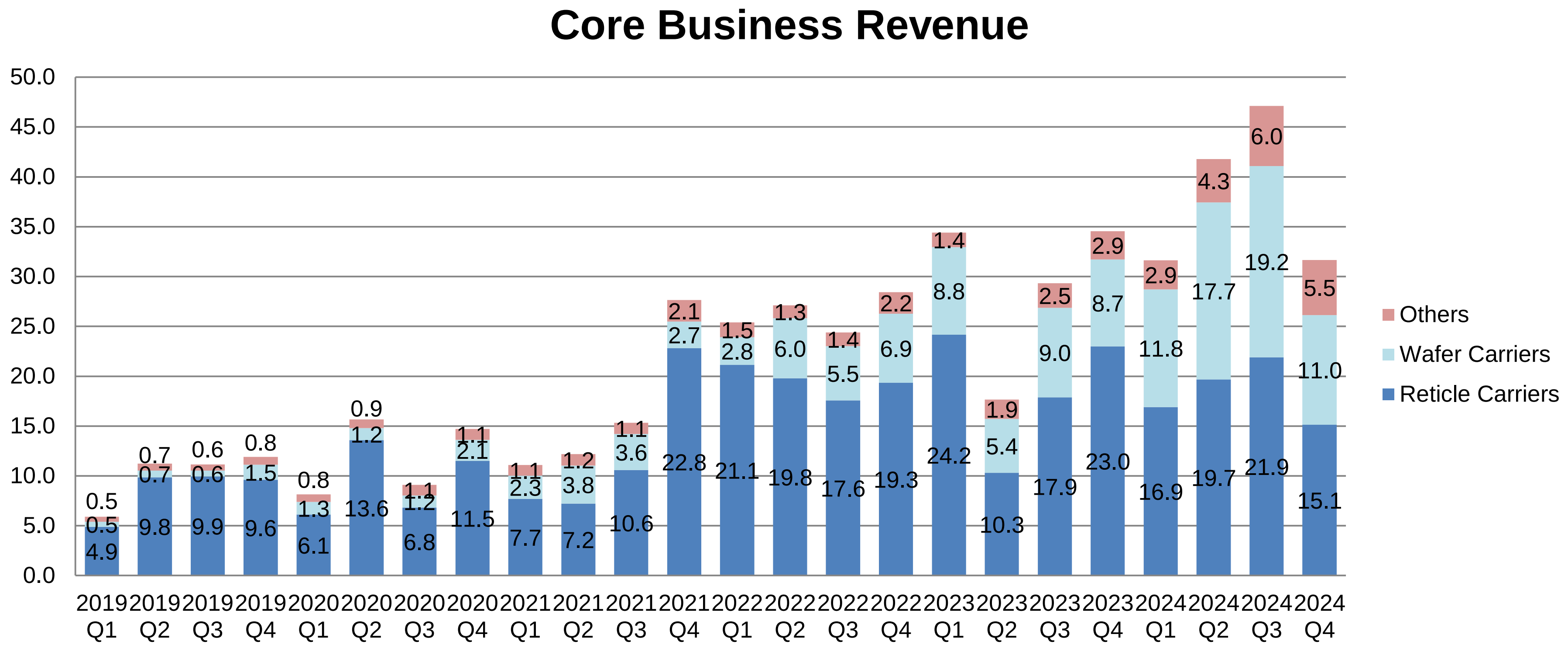
Gudeng

Consolidated Revenue



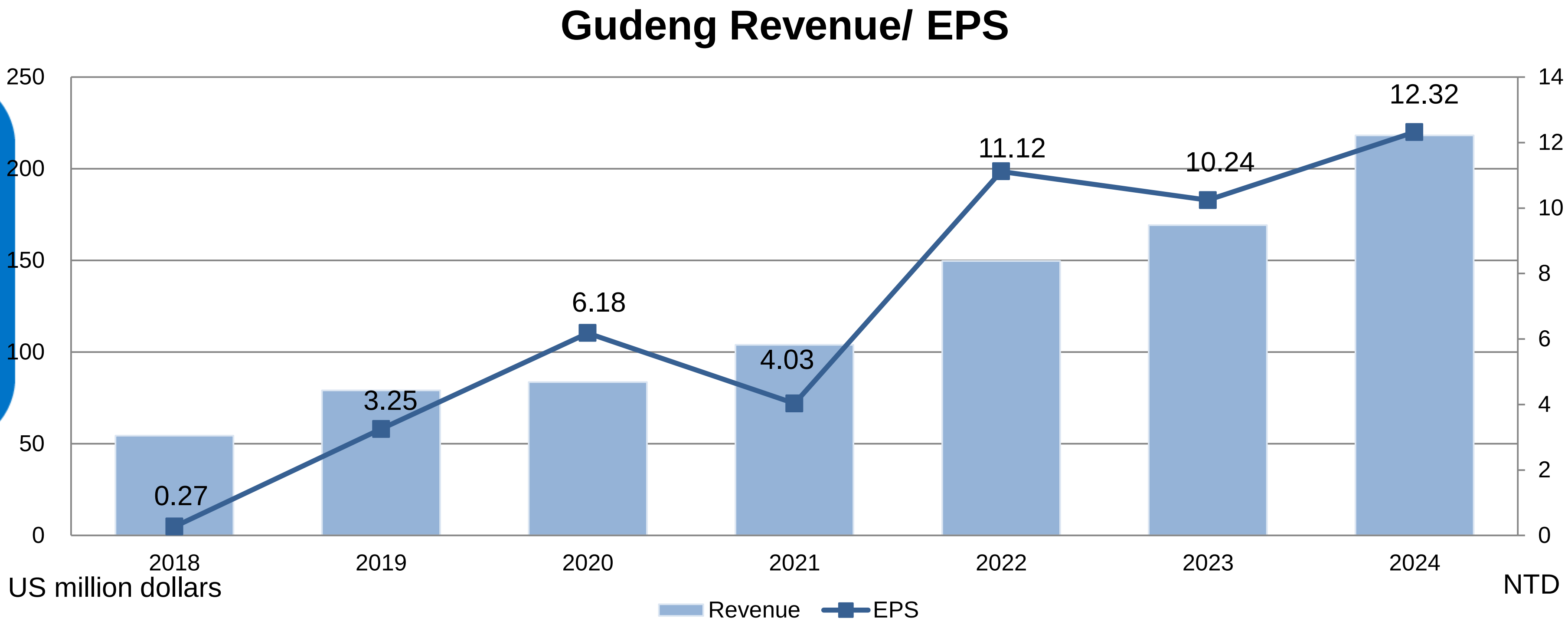
US million dollars

Gudeng Revenue (Quarterly)

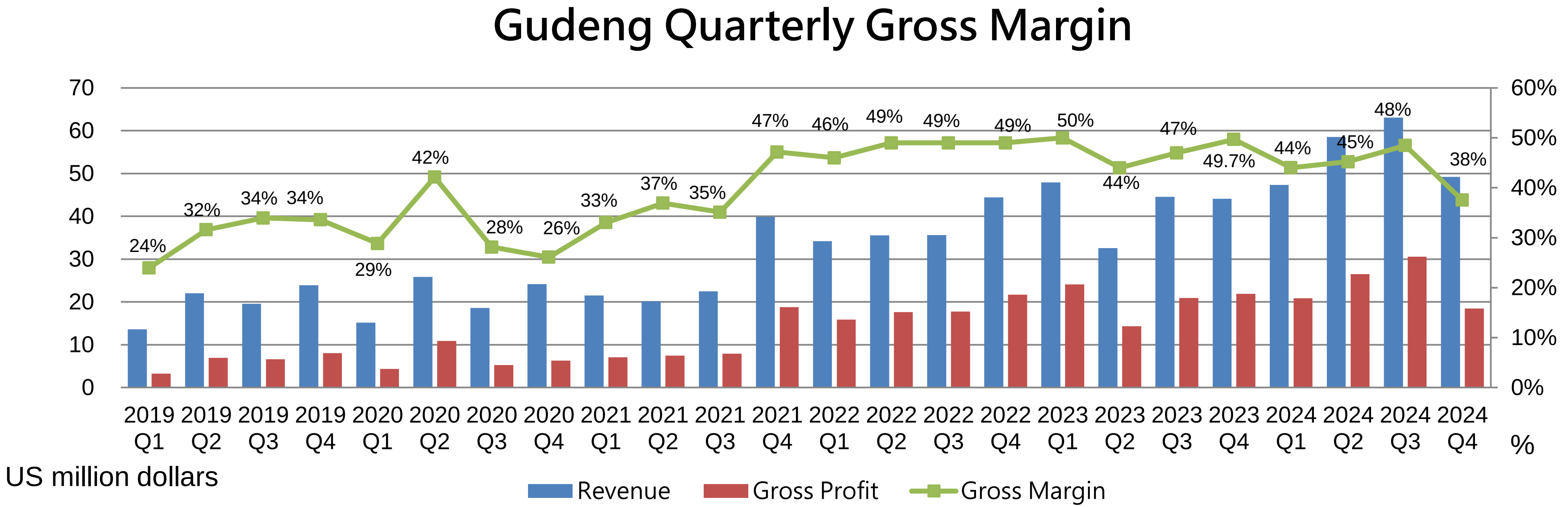


US million dollars

Gudeng Annual Revenue Performance



Gudeng Gross Margin (Quarterly)



Gudeng Group Revenue/ Gross Margin/ CapEx/ Asset

Gudeng

Year	Revenue	Gross Profit	Gross Margin	EPS	CapEx	Asset
2019	79,000	25,000	32%	3.24	3,167	160,667
2020	83,667	26,667	32%	6.18	37,667	207,667
2021	104,000	41,333	40%	4.03	68,700	316,667
2022	149,667	73,000	49%	11.12	24,367	406,667
2023	169,333	81,333	48%	10.24	43,467	543,000
2024	218,333	96,000	44%	12.32	-	712,333

US million dollars

Gudeng Group CapEx

Gudeng

Year	Land	Building	Building (Under construction)	Equipment	Other	Total
2019	0.87	1.27	-	0.47	0.57	3.18
2020	20.93	2.93	-	3.40	10.4	37.66
2021	48.43	1.27	9.43	5.63	3.93	68.69
2022	7.70	0.03	5.53	4.23	6.87	24.36
2023	6.83	0.73	18.70	9.23	7.97	43.46
2024 Q3	7.80	5.97	19.53	3.97	5.20	42.47

USD Million Dollar

Gudeng Expense and Margin Ratio

US Million Dollar	2024										2023				
	Q1	YoY%	Q2	YoY%	Q3	YoY%	Q4	YoY%	Total	YoY%	Q1	Q2	Q3	Q4	Total
Revenue	47.35	-1%	58.54	80%	63.13	42%	49.13	10%	169.02	35%	48.04	32.60	44.57	44.07	169.27
Cost	26.50	11%	32.06	74%	32.57	39%	30.63	28%	91.13	38%	23.91	18.45	23.47	22.13	87.97
Gross Margin	20.84	-14%	26.48	87%	30.57	45%	18.5	-19%	77.89	31%	24.13	14.15	21.1	21.93	81.3
OER	28%		23%		23%		30%		26%		20%	33%	30%	25%	27%
EPS	2.24		3.00		4.39		2.69		12.32		3.94	1.68	1.94	2.68	10.24

2024 Expense:
- To meet growth demands, M&A and related expenses have increased
- Due to demand from Greater China, the cost of delivery and related fee had increased.
- To increase production capacity, had purchase molds, machines and equipment, which depreciation had increased.

Major Customers & Products

Gudeng

GE Aviation

Manufacturing **Conducting Tubes, Check Valves, Fasteners**, as well as Machining parts, supporting the assemble of engines for GE

Honeywell

Providing different metal materials of **Conducting Tubes**, with in-house Chemical Processes, and Special Welding

Origin

High Barriers to Entry
High Gross Margin
Precision Machining

BOEING SPIRIT

Not only **Sheet Metals parts, Machining parts**, and **Tube Connectors**, but also providing **Plastic Injection**

Parker Aerospace

Expert in 3 ~ 5axis of milling and turning · manufacturing hydraulic components, such as **Cylinders, Differentials, Shafts, Piston** and **Rods**

Gudeng Aerospace Products

Gudeng

Parker

Hydraulic Control System
48%market share

GE Aerospace

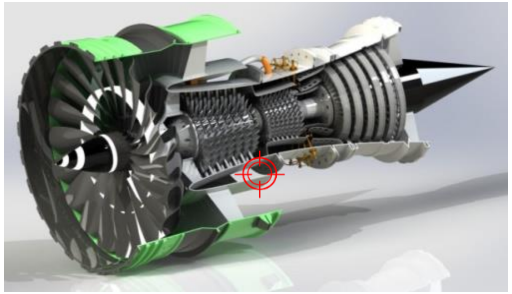
Honeywell AEROSPACE

ROLLS ROYCE

Parker

Fuel & Coolant Line
72% market share

Pratt & Whitney
A United Technologies Company



2025 Aerospace Outlook

Gudeng

SPIRIT AEROSYSTEMS

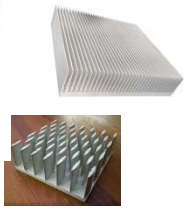
Cabin (Plastic)
36% market share

Parker
GE Aerospace

Engine Fuel Injector
91% market share

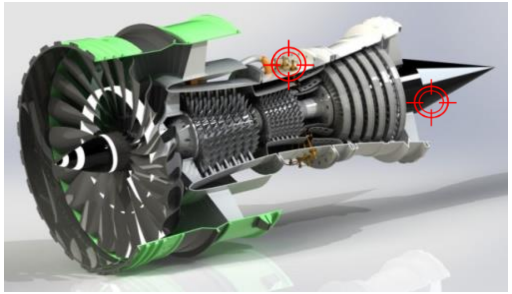
Cooling & Electrical system(Plastic)
37% market share

GE Aerospace



Parker

Braking System
63% market share



Liquid & Gas Discharge Pipeline
42%market share

Parker
Honeywell AEROSPACE
GE Aerospace

Gudeng Growth Blueprint-Highlights

Gudeng

Gudeng

Co-Creation

EUV Pod
2025 ~

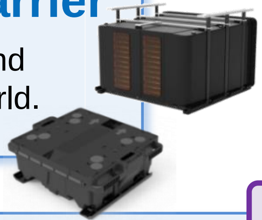
With the continuous expansion of advanced process, related demand is growing.

Wafer Carrier Solutions
2025 ~

The market share of our series of wafer carrier is rising worldwide. Became the baseline in the Greater China Market

Advance Packaging Carrier
2025 Q3 ~

Our complete solution of CoWoS and back-end 3D package leads the world.



New Technique
2026 ~

Continue to develop new technologies and expand new markets.

Aerospace Pioneer
2026 ~

Constantly expand customer base and challenge doubling revenue growth this year.

Gudeng Sustainability Performance

ESG Rating	
Listed/ OTC company	
A	
Economy	Environment
11-30%	31-50%
Society	Expose
11-30%	11-30%

2023 Reduce **33%** of Carbon Emissions

2023 Reduce **54%** of Water Usage

2023 Reduce **21%** of Industrial Waste

Homemade **Eco-Friendly Pallets Transport Cases**

Salary Increase Rate **7~9%** better than industry

Employees charity participating **382** times

Stipends reached **651** students

12 Industry-University Cooperation Items

2023 Revenue **US$162** million

2023 EPS **10.24 NTD**

RBA **Platinum Certification**

27TH **National Quality Awards**

Listed/ OTC company ESG Rating **A-Class**

Verification **TIPS A-Class 、ISO22301 、ISO20400**

Gudeng

ESG Report

2025/3/14

Gudeng Overall Performance

Gudeng

Revenue Growth：

US$ 32 million in 2019, US$ 145 million in 2022, US$ 162 million in 2023. As of 2024, revenue is about US$ 218 million , YOY 29%

Steadily Gross Profit Margin ：

Over 20% in 2018, 49% in 2022, 48% in 2023, 44% in 2024

Growth in EPS：

0.27 in 2018, 3.25 in 2019, 11.12 in 2022, 10.24 in 2023, 12.32 in 2024

Increasing Market Share：

Reticle carriers 70% worldwide, EUV Pod 85% worldwide, FOUP qualified by major customers, and 50% up of the customers in Greater China region apply Gudeng as the baseline

Prospect and Strategy

2025

- **Increasing market share in Wafer Carrier**, which bring growth in revenue
- Focus on advance process and become the main supplier for key customers
- With development of CoWoS, **shipment of Panel FOUP** have steadily **increased**
- Gudeng Total solution lead the market, group challenge higher revenue

2026

- **Key components completed verification, get long-term order** from customers,
- Strong revenue growth from CoWoS Carrier
- Revenue contribution from **Hi-NA EUV Pod and Immersion Cooling Tank**
- Continuing expanding factories, quickly responds to demands and supply locally

2027

- Leading **Advanced Packaging** market share continues to expand
- Expanding in **Semiconductor Consumables** market and provide a complete series of products for key customers.
- **Expanding special process** to complete Aerospace Roadmap
- Continuing focus on high-revenue markets and M&A

Thank You

www.gudeng.com